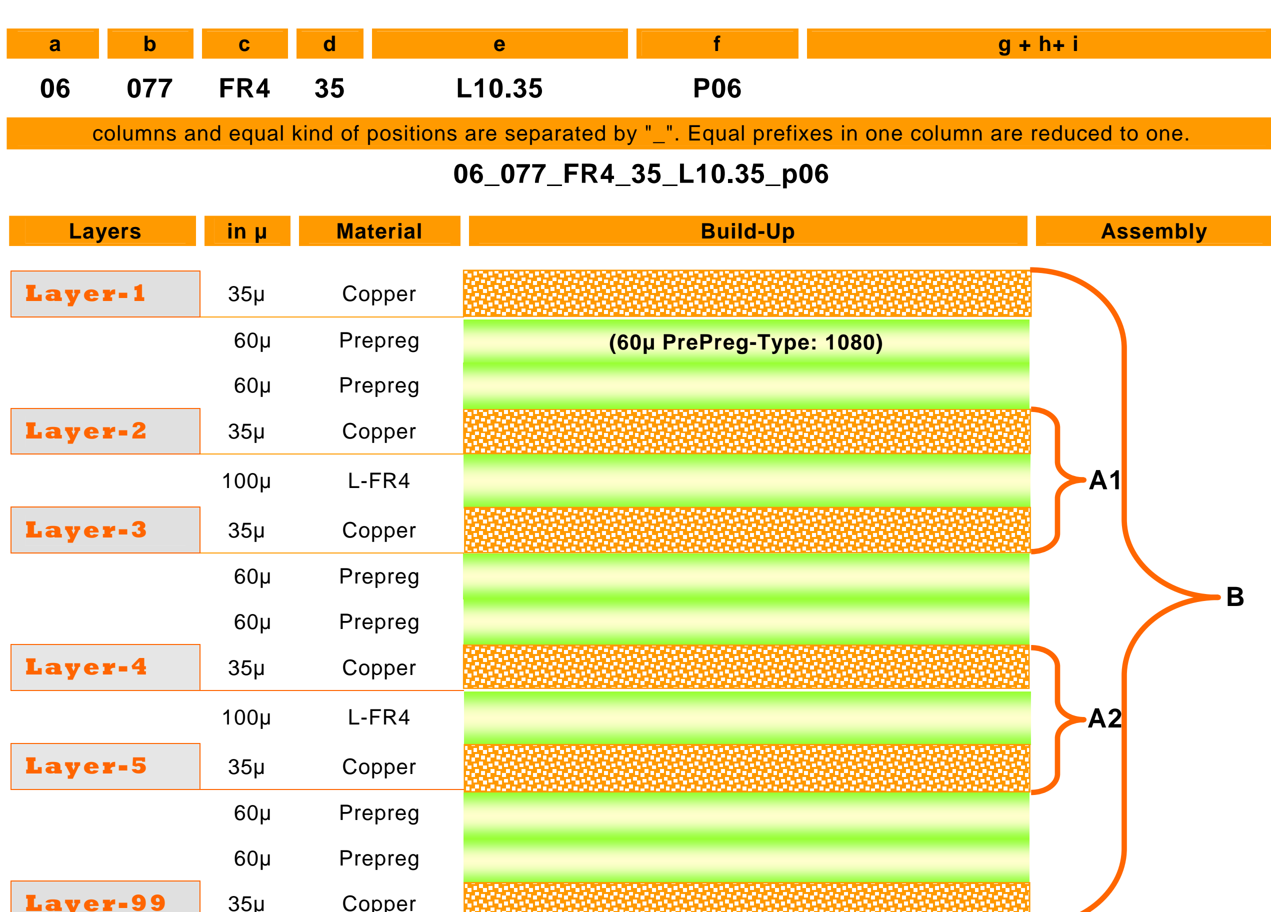
Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	**01**	**4.11.2001**	**1/1**

Schematic Key for Multilayer and HDI-Technology Build-Ups



a	b	c	d	e	f	g + h+ i
06	077	FR4	35	L10.35	P06	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_077_FR4_35_L10.35_p06

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	B
	60µ	Prepreg		B
Layer-2	35µ	Copper		A1, B
	100µ	L-FR4		A1, B
Layer-3	35µ	Copper		A1, B
	60µ	Prepreg		B
	60µ	Prepreg		B
Layer-4	35µ	Copper		A2, B
	100µ	L-FR4		A2, B
Layer-5	35µ	Copper		A2, B
	60µ	Prepreg		B
	60µ	Prepreg		B
Layer-99	35µ	Copper		B

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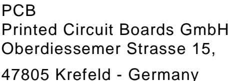

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